

STN790A

Medium current, high performance, low voltage PNP transistor

Features

- Very low collector to emitter saturation voltage
- DC current gain, h_{FE} >100
- 3 A continuous collector current
- 40 V breakdown voltage V_{(BR)CER}
- SOT-223 plastic package for surface mounting circuits in tape and reel packing

Applications

- Power management in portable equipment
- Voltage regulation in bias supply circuits
- Switching regulator in battery charger applications
- Heavy load driver

Description

The device in manufactured in low voltage PNP planar technology by using a "Base Island" layout. The resulting transistor shows exceptional high gain performance coupled with very low saturation voltage.

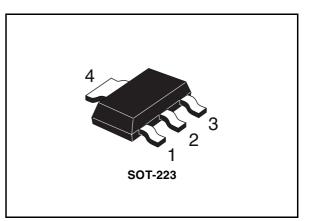


Figure 1. Internal schematic diagram

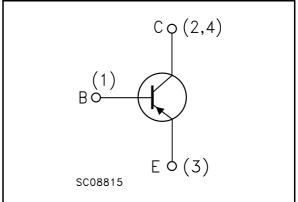


Table 1.Device summary

Order code	r code Marking	Package	Packaging	
STN790A	N790A	SOT-223	Tape and reel	

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Electrical ratings

Table 2.	Absolute maximum ratin	g
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Symbol	Parameter	Value	Unit
V _{CBO}	Collector-base voltage (I _E = 0)	-40	V
V _{CER}	Collector-emitter voltage ($R_{BE} = 47 \Omega$)	-40	V
V _{CEO}	Collector-emitter voltage (I _B = 0)	-30	V
V _{EBO}	Emitter-base voltage (I _C = 0)	-5	V
۱ _C	Collector current	-3	А
I _{CM}	Collector peak current (t _P < 5 ms)	-6	А
P _{tot}	Total dissipation at T _{amb} = 25 °C	1.6	W
T _{stg}	Storage temperature	-65 to 150	°C
Τ _J	Max. operating junction temperature	150	°C

Table 3. Thermal data

Symbol	Parameter	Value	Unit		
R _{thj-amb}	Thermal resistance junction-ambient (1) max	78	°C/W		
1 Device mounted on DCB case of 1 cm^2					

1. Device mounted on PCB area of 1 cm^2 .



2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)

Table 4. Electrical characteristics						
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{CBO}	Collector cut-off current $(I_E = 0)$	V _{CB} = -30 V V _{CB} = -30 V; T _C = 100 °C	;		-10 -100	μΑ μΑ
I _{EBO}	Emitter cut-off current $(I_{\rm C} = 0)$	V _{EB} = -4 V			-10	μA
V _{(BR)CEO} ⁽¹⁾	Collector-emitter breakdown voltage (I _B = 0)	I _C = -10 mA	-30			V
V _{(BR)CER} ⁽¹⁾	Collector-emitter breakdown voltage (R_{BE} = 47 Ω)	I _C = -10 mA	-40			V
V _{(BR)CBO}	Collector-base breakdown voltage (I _E = 0)	I _C = -100 μA	-40			V
V _{(BR)EBO}	Emitter-base breakdown voltage (I _C = 0)	I _E = -100 μA	-5			V
	Collector-emitter saturation voltage	$I_{\rm C} = -0.5 {\rm A} \qquad I_{\rm B} = -5 {\rm mA}$			-0.15	V
		I _C = -1.2 A I _B = -20 mA			-0.25	V
V _{CE(sat)} ⁽¹⁾		I _C = -2 A I _B = -20 mA			-0.5	V
- ()		$I_{\rm C} = -3 \text{ A}$ $I_{\rm B} = -100 \text{ mA}$	\		-0.7	V
		$I_{\rm C} = -3 \text{ A}$ $I_{\rm B} = -100 \text{ mA}$	N			
		T _J = 100 °C			-0.9	V
V _{BE(sat)} ⁽¹⁾	Base-emitter saturation voltage	I _C = -1 A I _B = -10 mA	N I I I I I I I I I I I I I I I I I I I	-0.8	-1	V
V _{BE(on)} ⁽¹⁾	Base-emitter on voltage	$I_{\rm C} = -1 \text{ A}$ $V_{\rm CE} = -2 \text{ V}$		-0.8	-1	V
		I _C = -10 mA V _{CE} = -2 V	100	200	400	
		$I_{C} = -500 \text{ mA}$ $V_{CE} = -2 \text{ V}$	100	200	400	
$h_{FE}^{(1)}$	DC current gain	$I_{\rm C} = -1 \ {\rm A}$ $V_{\rm CE} = -2 \ {\rm V}$				
		$I_{\rm C} = -2 \ {\rm A}$ $V_{\rm CE} = -1 \ {\rm V}$	100	160		
		$I_{\rm C} = -3 \text{ A}$ $V_{\rm CE} = -1 \text{ V}$	90	130		

Table 4.	Electrical	characteristics
	Liectrical	characteristics



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Iransition frequency		I _C = -50 mA V _{CE} = -5 V f = 50 MHz		100		MHz
	Resistive load					
t _d	Delay time	$I_{\rm C} = -3 {\rm A}$ $V_{\rm CC} = -20 {\rm V}$		180	220	ns
t _r	Rise time	I _{B1} = -I _{B2} = -60 mA		160	210	ns
t _s	Storage time	see Figure 8		250	300	ns
t _f	Fall time			80	100	ns

 Table 4.
 Electrical characteristics (continued)

1. Pulse duration = 300 μ s, duty cycle \leq 1.5%

2.1 Electrical characteristics (curves)

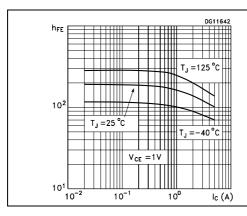


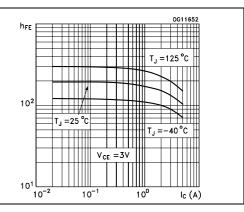
Figure 2. DC current gain

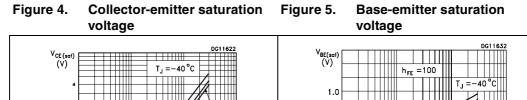
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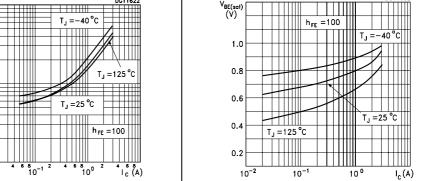
10⁻²

10-2

Figure 3. DC current gain







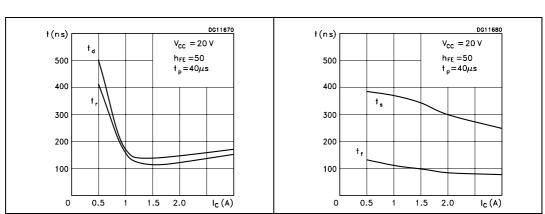
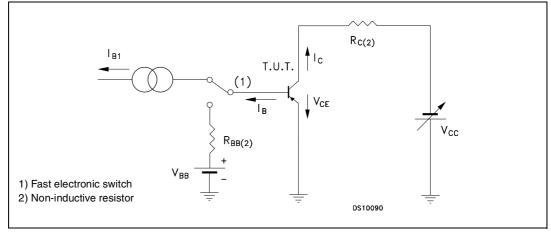


Figure 6. Switching time resistive load Figure 7. Switching time resistive load

2.2 Test circuit



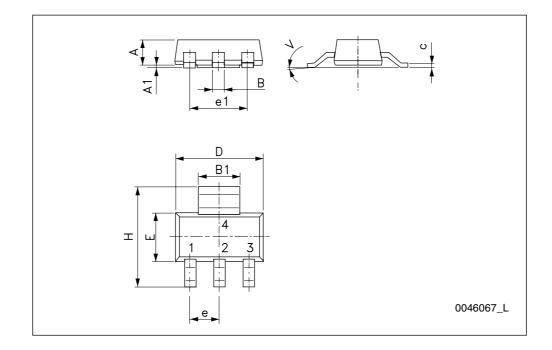


3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



	SOT-223 mechanical data				
DIM.		mm.			
Diwi.	min.	typ	max.		
А			1.80		
A1	0.02		0.1		
В	0.60	0.70	0.85		
B1	2.90	3.00	3.15		
с	0.24	0.26	0.35		
D	6.30	6.50	6.70		
е		2.30			
e1		4.60			
E	3.30	3.50	3.70		
н	6.70	7.00	7.30		
V			10 °		





4 Revision history

Table 5.Document revision history

Date	Revision	Changes
24-Mar-2006	3	Updated to new template
26-Jun-2008	4	Updated SOT-223 mechanical data.

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